

Features

· Internal control latches and address decoder

Short set-up and hold times

Wide operating voltage: 4.5V to 13.2V

12Vpp analog signal capability

R_{ON} 65Ω max. @ V_{DD}=12V, 25°C

• $\Delta R_{ON} \le 10\Omega @ V_{DD} = 12V, 25^{\circ}C$

· Full CMOS switch for low distortion

· Minimum feedthrough and crosstalk

Separate analog and digital reference supplies

Low power consumption ISO-CMOS technology

Applications

- · Key systems
- · PBX systems
- · Mobile radio
- Test equipment /instrumentation
- Analog/digital multiplexers
- · Audio/Video switching

ISSUE2 March 1997

Ordering Information

MT8815AE 40 Pin Plastic DIP MT8815AP 44 Pin PLCC

-40° to 85°C

Description

The Zarlink MT8815 is fabricated in Zarlink's ISO-CMOS technology providing low power dissipation and high reliability. The device contains a 8 x 12 array of crosspoint switches along with a 7 to 96 line decoder and latch circuits. Any one of the 96 switches can be addressed by selecting the appropriate seven address bits. The selected switch can be turned on or off by applying a logical one or zero to the DATA input. V_{SS} is the ground reference of the digital inputs. The range of the analog signal is from V_{DD} to V_{EE} .

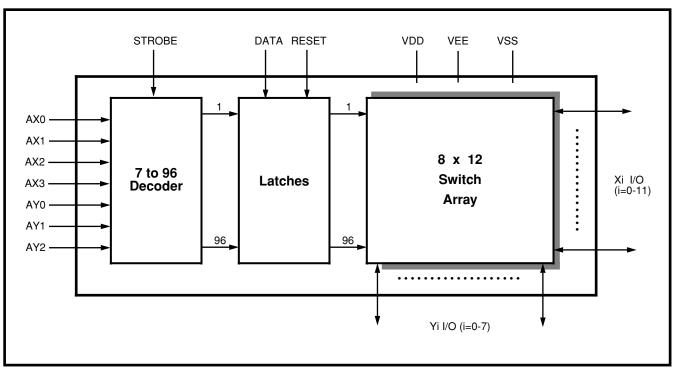


Figure 1 - Functional Block Diagram

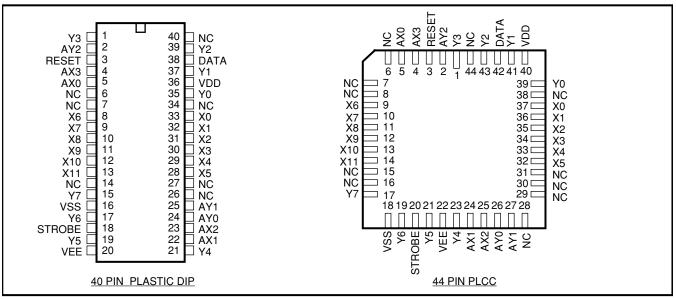


Figure 2 - Pin Connections

Pin Description

Pir	า #		
PDIP	PLCC	Name	Description
1	1	Y3	Y3 Analog (Input/Output): this is connected to the Y3 column of the switch array.
2	2	AY2	Y2 Address Line (Input).
3	3	RESET	Master RESET (Input): this is used to turn off all switches. Active High.
4,5	4,5	AX3,AX0	X3 and X0 Address Lines (Inputs): these are used to select X3 and X0 rows of switches.
6,7	6-8	NC	No Connection.
8-13	9-14	X6-X11	X6-X11 Analog (Inputs/Outputs): these are connected to the X6-X11 rows of the switch array.
14	15,16	NC	No Connection
15	17	Y7	Y7 Analog (Input/Output): this is connected to the Y7 column of the switch array.
16	18	V _{SS}	Digital Ground Reference (Input).
17	19	Y6	Y6 Analog (Input/Output): this is connected to the Y6 column of the switch array.
18	20	STROBE	STROBE (Input) : enables function selected by address and data. Address must be stable before STROBE goes high and DATA must be stable on the falling edge of the STROBE. Active High.
19	21	Y5	Y5 Analog (Input/Output): this is connected to the Y5 column of the switch array.
20	22	V _{EE}	Negative Power Supply.
21	23	Y4	Y4 Analog (Input/Output): this is connected to the Y4 column of the switch array.
22, 23	24,25	AX1,AX2	X1 and X2 Address Lines (Inputs).
24, 25	26,27	AY0,AY1	Y0 and Y1 Address Lines (Inputs).
26, 27	28-31	NC	No Connection.
28 - 33	32-37	X5-X0	X5-X0 Analog (Inputs/Outputs): these are connected to the X5-X0 rows of the switch array.
34	38	NC	No Connection.
35	39	Y0	YO Analog (Input/Output): this is connected to the YO column of the switch array.
36	40	V_{DD}	Positive Power Supply.
37	41	Y1	Y1 Analog (Input/Output): this is connected to the Y1 column of the switch array.

Pin Description

Pin #		Name	Description
PDIP	PLCC	Name	Description
38	42	DATA	DATA (Input) : a logic high input will turn on the selected switch and a logic low will turn off the selected switch. Active High.
39	43	Y2	Y2 Analog (Input/Output): this is connected to the Y2 column of the switch array.
40	44	NC	No Connection.

Functional Description

The MT8815 is an analog switch matrix with an array size of 8∞12. The switch array is arranged such that there are 8 columns by 12 rows. The columns are referred to as the Y inputs/outputs and the rows are the X inputs/outputs. The crosspoint analog switch array will interconnect any X I/O with any Y I/O when turned on and provide a high degree of isolation when turned off. The control memory consists of a 96 bit write only RAM in which the bits are selected by the address inputs (AY0-AY2, AX0-AX3). Data is presented to the memory on the DATA input. Data is asynchronously written into memory whenever the STROBE input is high and is latched on the falling edge of STROBE. A logical "1" written into a memory cell turns the corresponding crosspoint switch on and a logical "0" turns the crosspoint off. Only the crosspoint switches corresponding to the addressed memory location are altered when data is written into memory. The remaining switches retain their previous states. Any combination of X and Y inputs/outputs can be interconnected by establishing appropriate patterns in the control memory. A logical "1" on the RESET input will asynchronously return all memory locations to logical "0" turning off all Two voltage reference pins crosspoint switches. $(V_{SS} \text{ and } V_{FF})$ are provided for the MT8815 to enable switching of negative analog signals. The range for digital signals is from V_{DD} to V_{SS} while the range for analog signals is from V_{DD} to V_{EE} . V_{SS} and V_{EE} pins can be tied together if a single voltage reference is needed.

Address Decode

The seven address inputs along with the STROBE are logically ANDed to form an enable signal for the resettable transparent latches. The DATA input is buffered and is used as the input to all latches. To write to a location, RESET must be low while the address and data are set up. Then the STROBE input is set high and then low causing the data to be latched. The data can be changed while STROBE is high, however, the corresponding switch will turn on and off in accordance with the DATA input. DATA must be stable on the falling edge of STROBE in order for correct data to be written to the latch.

Absolute Maximum Ratings*- Voltages are with respect to V_{EE} unless otherwise stated.

	Parameter	Symbol	Min	Max	Units
1	Supply Voltage	V_{DD} V_{SS}	-0.3 -0.3	15.0 V _{DD} +0.3	V V
2	Analog Input Voltage	V _{INA}	-0.3	V _{DD} +0.3	V
3	Digital Input Voltage	V _{IN}	V _{SS} -0.3	V _{DD} +0.3	V
4	Current on any I/O Pin	I		±15	mA
5	Storage Temperature	T _S	-65	+150	°C
6	Package Power Dissipation PLASTIC DIP	P _D		0.6	W

^{*} Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

Recommended Operating Conditions - Voltages are with respect to V_{EE} unless otherwise stated.

	Characteristics	Sym	Min	Тур	Max	Units	Test Conditions
1	Operating Temperature	T _O	-40	25	85	°C	
2	Supply Voltage	V _{DD}	4.5		13.2	V	
		V_{SS}	V_{EE}		V _{DD} -4.5	V	
3	Analog Input Voltage	V _{INA}	V_{EE}		V_{DD}	V	
4	Digital Input Voltage	V _{IN}	V_{SS}		V_{DD}	٧	

$\textbf{DC Electrical Characteristics}^{\dagger} \textbf{.} \ \ \text{Voltages are with respect to V}_{EE} \textbf{=V}_{SS} \textbf{=0V}, \ V_{DD} \textbf{=12V} \textbf{ unless otherwise stated}.$

	Characteristics	Sym	Min	Typ [‡]	Max	Units	Test Conditions
1	Quiescent Supply Current	I _{DD}		1	100	μΑ	All digital inputs at $V_{IN}=V_{SS}$ or V_{DD}
				0.4	1.5	mA	All digital inputs at V_{IN} =2.4V + V_{SS} ; V_{SS} =7.0V
				5	15	mA	All digital inputs at V _{IN} =3.4V
2	Off-state Leakage Current (See G.9 in Appendix)	l _{OFF}		±1	±500	nA	$IV_{Xi} - V_{Yj}I = V_{DD} - V_{EE}$ See Appendix, Fig. A.1
3	Input Logic "0" level	V _{IL}			0.8+V _S S	V	V _{SS} =7.5V; V _{EE} =0V
4	Input Logic "1" level	V _{IH}	2.0+V _{SS}			V	V_{SS} =6.5V; V_{EE} =0V
5	Input Logic "1" level	V _{IH}	3.3			V	
6	Input Leakage (digital pins)	I _{LEAK}		0.1	10	μΑ	All digital inputs at $V_{IN} = V_{SS}$ or V_{DD}

DC Electrical Characteristics- Switch Resistance - V_{DC} is the external DC offset applied at the analog I/O pins.

	Characteristics	Sym	25	5°C	70)°C	85	5°C	Units	Test Conditions
			Тур	Max	Тур	Max	Тур	Max		
1	$ \begin{array}{lll} \text{On-state} & \text{V}_{\text{DD}}\text{=}12\text{V} \\ \text{Resistance} & \text{V}_{\text{DD}}\text{=}10\text{V} \\ & \text{V}_{\text{DD}}\text{=}5\text{V} \\ \text{(See G.1, G.2, G.3 in} \\ \text{Appendix)} \end{array} $	R _{ON}	45 55 120	65 75 185		75 85 215		80 90 225	Ω Ω Ω	$V_{SS}=V_{EE}=0V, V_{DC}=V_{DD}/2,$ $IV_{Xi}-V_{Yj}I=0.4V$ See Appendix, Fig. A.2
2	Difference in on-state resistance between two switches (See G.4 in Appendix)	ΔR _{ON}	5	10		10		10	Ω	V_{DD} =12V, V_{SS} = V_{EE} =0, V_{DC} = V_{DD} /2, IV_{Xi} - $V_{Yj}I$ = 0.4V See Appendix, Fig. A.2

[†] DC Electrical Characteristics are over recommended temperature range. ‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

AC Electrical Characteristics† - Crosspoint Performance-Voltages are with respect to V_{DD}=5V, V_{SS}=0V, V_{FF}=-7V, unless otherwise stated.

	Characteristics	Sym	Min	Typ [‡]	Max	Units	Test Conditions
1	Switch I/O Capacitance	C _S		20		pF	f=1 MHz
2	Feedthrough Capacitance	C _F		0.2		pF	f=1 MHz
3	Frequency Response Channel "ON" 20LOG(V _{OUT} /V _{Xi})=-3dB	F _{3dB}		45		MHz	Switch is "ON"; $V_{INA} = 2Vpp$ sinewave; $R_L = 1k\Omega$ See Appendix, Fig. A.3
4	Total Harmonic Distortion (See G.5, G.6 in Appendix)	THD		0.01		%	Switch is "ON"; $V_{INA} = 2Vpp$ sinewave f= 1kHz; R_L =1k Ω
5	Feedthrough Channel "OFF" Feed.=20LOG (V _{OUT} /V _{Xi}) (See G.8 in Appendix)	FDT		-95		dB	All Switches "OFF"; V_{INA} = 2Vpp sinewave f= 1kHz; R_L = 1k Ω . See Appendix, Fig. A.4
6	Crosstalk between any two channels for switches Xi-Yi and	X _{talk}		-45		dB	V_{INA} =2Vpp sinewave f= 10MHz; $R_L = 75\Omega$.
	Xj-Yj. Xtalk=20LOG (V _{Yi} /V _{Xi}).			-90		dB	V_{INA} =2Vpp sinewave f= 10kHz; R _L = 600 Ω .
	(See G.7 in Appendix).			-85		dB	V_{INA} =2Vpp sinewave f= 10kHz; R _L = 1k Ω .
				-80		dB	V_{INA} =2Vpp sinewave f= 1kHz; R _L = 10k Ω . Refer to Appendix, Fig. A.5 for test circuit.
7	Propagation delay through switch	t _{PS}			30	ns	$R_L=1k\Omega; C_L=50pF$

AC Electrical Characteristics[†] - Control and I/O Timings- Voltages are with respect to V_{DD}=5V, V_{SS}=0V, V_{EE}=-7V, unless otherwise stated.

	Characteristics	Sym	Min	Typ [‡]	Max	Units	Test Conditions
1	Control Input crosstalk to switch (for DATA, STROBE, Address)	CX _{talk}		30		mVpp	V_{IN} =3V squarewave; R _{IN} =1k Ω , R _L =10k Ω . See Appendix, Fig. A.6
2	Digital Input Capacitance	C _{DI}		10		pF	f=1MHz
3	Switching Frequency	F _O			20	MHz	
4	Setup Time DATA to STROBE	t _{DS}	10			ns	$R_L = 1k\Omega$, $C_L = 50pF$ ^①
5	Hold Time DATA to STROBE	t _{DH}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ^①
6	Setup Time Address to STROBE	t _{AS}	10			ns	$R_L=1k\Omega$, $C_L=50pF$ ^①
7	Hold Time Address to STROBE	t _{AH}	10			ns	$R_L = 1k\Omega$, $C_L = 50pF$ ^①
8	STROBE Pulse Width	t _{SPW}	20			ns	$R_L=1k\Omega$, $C_L=50pF$ ^①
9	RESET Pulse Width	t _{RPW}	40			ns	$R_L=1k\Omega$, $C_L=50pF$ ^①
10	STROBE to Switch Status Delay	t _S		40	100	ns	$R_L = 1k\Omega$, $C_L = 50pF$ ^①
11	DATA to Switch Status Delay	t _D		50	100	ns	$R_L=1k\Omega$, $C_L=50pF$ ^①
12	RESET to Switch Status Delay	t _R		35	100	ns	$R_L = 1k\Omega$, $C_L = 50pF$ ^①

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details. ‡ Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing. Crosstalk measurements are for Plastic DIPS only, crosstalk values for PLCC packages are approximately 5dB better.

[†] Timing is over recommended temperature range. See Fig. 3 for control and I/O timing details.

Digital Input rise time (tr) and fall time (tf) = 5ns.

† Typical figures are at 25°C and are for design aid only; not guaranteed and not subject to production testing.

Refer to Appendix, Fig. A.7 for test circuit.

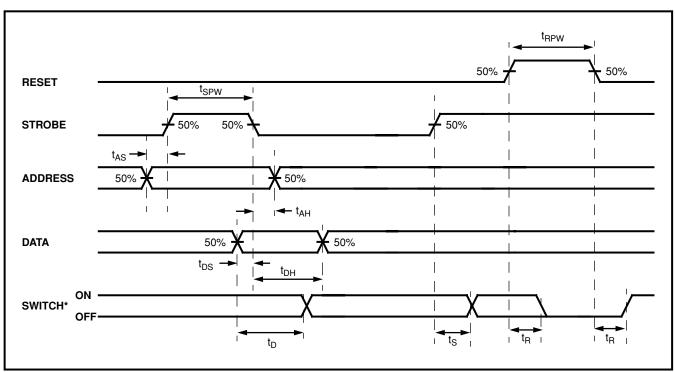


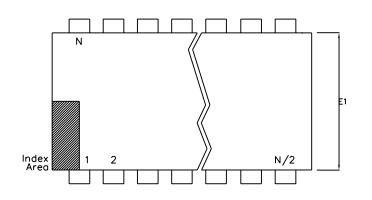
Figure 3 - Control Memory Timing Diagram

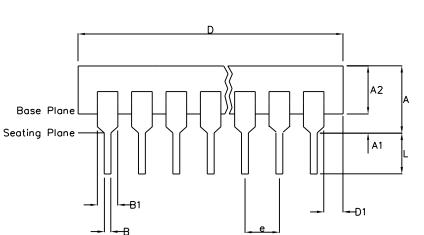
^{*} See Appendix, Fig. A.7 for switching waveform

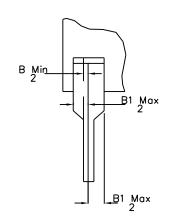
AX0	AX1	AX2	AX3	AY0	AY1	AY2	Connection
0	0	0	0	0	0	0	X0-Y0
1	0	0	0	0	0	0	X1-Y0
0	1	0	0	0	0	0	X2-Y0
1	1	0	0	0	0	0	X3-Y0
0	0	1	0	0	0	0	X4-Y0
1	0	1	0	0	0	0	X5-Y0 ①
0	1 1	1	0	0	0	0	No Connection (
1	1 1	1	0	0	0	0	No Connection
0	0	0	1	0	0	0	X6-Y0
1	0	0	1	0	0	0	X7-Y0
0] !	0	1	0	0	0	X8-Y0
1	1	0	1	0	0	0	X9-Y0
0	0	1	1	0	0	0	X10-Y0
1	0	1	1	0	0	0	X11-Y0 ①
0]	1	1	0	0	0	No Connection ①
!	1	l I	!	U			No Connection U
0	0	0	0	1	0	0	X0-Y1 ↓ ↓
1	0	1	1	1	0	0	X11-Y1
0	0	0	0	0	1	0	X0-Y2 ↓↓
1	0	1	1	0	1	0	X11-Y2
0	0	0 ↓	0 ↓	1	1	0	X0-Y3 ↓↓
1	0	1	1	1	1	0	X11-Y3
0	0	0	0	0	0	1	X0-Y4 ↓ ↓
1	0	1	1	0	0	1	X11-Y4
0	0	0	0	1	0	1	X0-Y5 ↓↓
1	0	1	1	1	0	1	X11-Y5
0	0	0	0	0	1	1	X0-Y6 ↓↓
1	0	1	1	0	1	1	X11-Y6
0	0	0	0	1	1	1	X0-Y7 ↓↓
1	0	1	1	1	1	1	X11-Y7

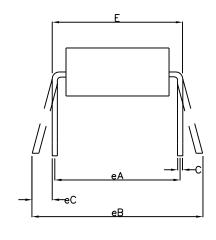
Table 1. Address Decode Truth Table

 $^{^{\}scriptsize \scriptsize (1)}$ This address has no effect on device status.









	Min	Max	Min	Max		
	mm	mm	<u>Inches</u>	Inches		
Α		6.35		0.250		
A1	0.38		0.015			
Α2	3.18	4.95	0.125	0.195		
В	0.36	0.56	0.014	0.022		
B1	0.76	1.78	0.030	0.070		
С	0.20	0.38	0.008	0.015		
D	50.29	53.21	1.980	2.095		
D1	0.13		0.005			
E	15.24	15.88	0.600	0.625		
E1	12.32	14.73	0.485	0.580		
е	2.54	BSC	0.100	BSC		
eА	15.24	BSC	0.600	BSC		
eВ		17.78		0.700		
L	2.92	5.08	0.115	0.200		
N	4	0	4	0		
Confo	Conforms to Jedec MS-011AC ISS.B					

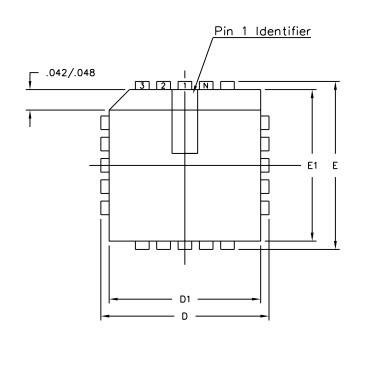
Notes:

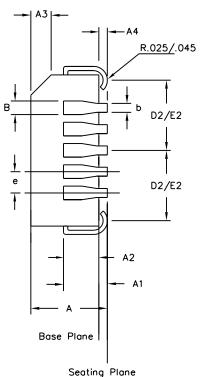
Controlling Dimensions are in inches
 Dimension A, A1 and L are measured with the package seated in the Seating Plane
 Dimensions D & E1 do not include mould flash or protrusions. Mould flash or protrusion shall not exceed 0.010 inch.
 Dimensions E & eA are measured with leads constrained to be perpendicular to plane T.
 Dimensions eB & eC are measured at the lead tips with the leads unconstrained; eC must be zero or greater.

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APPRD.					



	Package Code DA
Previous package codes	Package Outline for 40 lead PDIP
	GPD00073





	Control D	imensions	Altern. Di	mensions		
Symbol	in inc	hes	in millimetres			
	MIN	MAX	MIN	MAX		
Α	0.165	0.180	4.19	4.57		
Α1	0.090	0.120	2.29	3.05		
Α2	0.062	0.083	1.57	2.11		
А3	0.042	0.056	1.07	1.42		
Α4	0.020	ı	0.51	1		
D	0.685	0.695	17.40	17.65		
D1	0.650	0.656	16.51	16.66		
D2	0.291	0.319	7.39	8.10		
Ε	0.685	0.695	17.40	17.65		
E1	0.650	0.656	16.51	16.66		
E2	0.291	0.319	7.39	8.10		
В	0.026	0.032	0.66	0.81		
Ь	0.013	0.021	0.33	0.53		
е	0.050 BSC 1.27 BSC					
	Pin features					
ND	11					
NE	11					
Ν	44					
Note	Square					
Conforms to JEDEC MS-018AC Iss. A						

Notes:

- 1. All dimensions and tolerances conform to ANSI Y14.5M-1982
- 2. Dimensions D1 and E1 do not include mould protrusions. Allowable mould protrusion is 0.010" per side. Dimensions D1 and E1 include mould protrusion mismatch and are determined at the parting line, that is D1 and E1 are measured at the extreme material condition at the upper or lower parting line.
- 3. Controlling dimensions in Inches.
- 4. "N" is the number of terminals.
- 5. Not To Scale
- 6. Dimension R required for 120° minimum bend.

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ISSUE	1	2	3		Previous package codes	Package Outline for
ACN	5958	207470	213094	ZARLINK SEMICONDUCTOR	HP / P	44 lead PLCC
DATE	15Aug94	10Sep99	15Jul02	Jamies Nyselisk	,	
APPRD.						GPD00003



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